



# Product Change Notification

**Change Notification #: 115946 - 00**

**Change Title: Intel® Gigabit ET Dual Port Server Adapter,  
Product Code, E1G42ETG1P20, MM# 897969**

**Intel® Gigabit ET2 Quad Port Server Adapter,  
Product Code, E1G44ETG2P20, MM# 907808**

**Intel® Ethernet Network Connection OCP I357-T4,  
Product Code, I357T4OCPG1P5, MM# 948352**

**Intel® Ethernet Network Connection OCP X527-DA2,  
Product Code, X527DA2OCPG1P5, MM# 950126**

**Intel® Ethernet Network Connection OCP X527-DA4,  
Product Code, X527DA4OCPG1P5, MM# 950127**

**Intel® Ethernet Network Connection OCP X557-T2,  
Product Code, X557T2OCPG1P5, MM# 950179**

**Intel® Ethernet Server Adapter X520-DA1, Product  
Code X520DA1OCP, MM# 924882**

**Intel® Ethernet Server Adapter X520-DA2, Product  
Code, X520DA2OCP, MM# 930213**

**PCN 115946-00, Label, Product Marking, Label Updates  
on all, with a mark change on only two specific products**

**Date of Publication: December 04, 2017**

## Key Characteristics of the Change:

Label, Product Marking

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Dec 31, 2017
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## Description of Change #1 to the Customer:

The Intel products listed in the Product Affected table below will undergo the following changes:

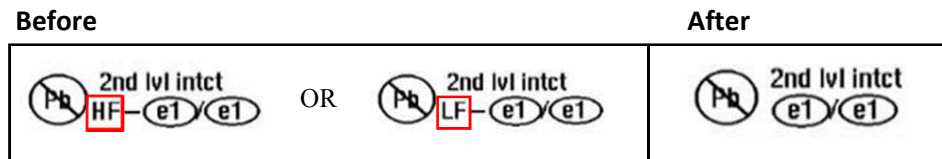
1. The Taiwan BSMI has a new RoHS declaration and inspection mark. The BSMI logo will be updated on the board level, with a cover up label, and on the packaging label if it currently exists there.



2. Ukraine has a new RoHS declaration that will be added to the outer box packaging label.



3. In order to align all our products and labels with the JEDEC 609A Standard for board assembly marking, we will remove the HF or LF (as applicable) from all outer box packaging labels if it currently exists there.



## Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® Gigabit ET Dual Port Server Adapter	E1G42ETG1P20	897969
Intel® Gigabit ET2 Quad Port Server Adapter	E1G44ETG2P20	907808
Intel® Ethernet Network Connection OCP I357-T4	I357T4OCPG1P5	948352
Intel® Ethernet Network Connection OCP X527-DA2	X527DA2OCPG1P5	950126
Intel® Ethernet Network Connection OCP X527-DA4	X527DA4OCPG1P5	950127
Intel® Ethernet Network Connection OCP X557-T2	X557T2OCPG1P5	950179
Intel® Ethernet Server Adapter X520-DA1	X520DA1OCP	924882
Intel® Ethernet Server Adapter X520-DA2	X520DA2OCP	930213

## Description of Change #2 to the Customer (select products only):

In addition to the label changes mentioned above, there are two Intel products (ie Intel® Ethernet Server Adapter X520-DA1 and Intel® Ethernet Server Adapter X520-DA2) which will undergo a material change on the finished good mark.

As per the Intel Corporate Green Initiative, Intel is moving its products to a RoHS Compliant 100% lead-free process which impacted several of the flip-chip silicon product lines. The current silicon products are listed as 'exempt' based on the EU RoHS exemption for FLI leaded parts. However, this change removed that RoHS exemption. There is no impact on the silicon's function, electrical performance, mechanical use or stated reliability. Intel has qualified and certified this change in the same way as all products supplied to our customers. There is no form-fit-function change for any of the impacted silicon. FLI (First Level Interconnect) material will change from Lead (Pb) based solder bump technology to Pb-Free (Sn/Ag) technology. There is no change to the second level interconnects for these products. This change affects First Level Interconnects only. The transition from eutectic to lead free at the FLI style of the product marking will change. The mark will go to a laser mark on swatch versus an ink stamp on substrate as illustrated below.



Niantic Eutectic (Pb-bumps)



Niantic Lead-free

**Note:** As a result of these changes directly above (Change#2), the PBA (printed board assembly) and TA (top assembly) numbers will roll as noted in the affected products table within this PCN. If the PBA/TA numbers are printed on any product or box labels, those will show the PBA/TA dash roll as well.

## Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	TA# Pre-Change	PBA# Pre-Change	TA# Post Change	PBA# Post Change	MM#
Intel® Ethernet Server Adapter X520-DA1	X520DA1OCP	G97415-005	G94326-006	G97415-006	G94326-007	924882
Intel® Ethernet Server Adapter X520-DA2	X520DA2OCP	G97416-005	G96215-006	G97416-006	G96215-007	930213

## Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers.

Customers can expect to receive mixed inventory until current inventory levels are depleted.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

## PCN Revision History:

**Date of Revision:**  
December 04, 2017

**Revision Number:**  
00

**Reason:**  
Originally Published PCN



# Product Change Notification

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The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apacgccb@intel.com](mailto:apacgccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

**Japan Email:** [jccb.ijkk@intel.com](mailto:jccb.ijkk@intel.com)

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